Attorney Docket No: 2557-000222/US

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

1. (Currently Amended) An integrated burn-in test method for testing a multi-chip package, comprising:

uploading an integrated burn-in test program to burn-in equipment for testing the multichip package <u>having multiple kinds of semiconductor devices</u>; and

conducting a test of the multi-chip package on each of the semiconductor devices using the integrated burn-in test program.

- 2. (Cancelled)
- 3. (Currently Amended) The method of claim 1, wherein the semiconductor device is a semiconductor chip the multiple kinds of semiconductor devices include one or more of a non-volatile memory, SRAM, and DRAM.
- 4. (Original) The method of claim 1, wherein the multi-chip package performs a memory function.
- 5. (Currently Amended) The method of claim 1, wherein the test is conducted for each of the semiconductor devices of the multi-chip package at a different temperature.

- 6. (Currently Amended) The method of claim 1, wherein the multi-chip package is loaded on a burn-in board and the burn-in board is loaded in the a chamber of burn-in equipment.
- 7. (Original) The method of claim 1, wherein the multi-chip package is in the form of a TBGA (thin ball grid array).
- 8. (Currently Amended) The method of claim 1, wherein the integrated burn-in test program uses a multiplexer selection function for applying a desired test condition during testing of each of the semiconductor devices.
- 9. (Original) The method of claim 1, wherein the integrated burn-in test program has an I/O masking function for blocking some I/O terminals.
- 10. (Currently Amended) The method of claim 1, wherein the integrated burn-in test program has a function of setting a burn-in temperature condition for different kinds each of the semiconductor devices.
- 11. (Currently Amended) The method of claim 6, wherein after loading the multi-chip package on the burn-in board to a the chamber of the burn-in equipment, a contact test is conducted to examine whether an electrical connection of the burn-in board is correct.
- 12. (Original) The method claimed in claim 1, wherein the burn-in test is a monitoring burn-in test.

- 13. (Original) The method of claim 1, wherein the integrated burn-in test program requires only one time bin sorting based on the burn-in test result.
- 14. (Currently Amended) An integrated burn-in test method for testing a multi-chip package, comprising:

uploading an integrated burn-in test program to test different kinds of semiconductor devices the multi-chip package having multiple kinds of semiconductor devices to burn-in equipment;

conducting a contact test for a burn-in board to examine an electrical connection;

conducting a burn-in test for the different kinds each of the semiconductor devices using a multiplex selection function of the integrated burn-in test program loaded to the burn-in equipment;

ending the burn-in test for different kinds of semiconductor devices; and bin sorting the multi-chip package based on the burn-in test result.

- 15. (Currently Amended) The method of claim 14, wherein when the burn-in test for different kinds each of the semiconductor devices are is performed sequentially and the integrated burn-in test program controls the chamber temperature according to a test temperature for an individual each of the semiconductor devices.
- 16. (Currently Amended) The method of claim 14, wherein each of the semiconductor devices performs a memory function.

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- 17. (Original) The method of claim 14, wherein the integrated burn-in test program has an I/O masking function for blocking some I/O terminals.
- 18. (Original) The method of claim 17, wherein each semiconductor device of the multi-chip package has a different number of I/O terminal pins.
- 19. (Original) The method of claim 14, wherein the multi-chip package is in the form of a TBGA (thin ball grid array).
- 20. (Original) The method of claim 14, wherein the burn-in test is a monitoring burn-in test.
- 21. (Currently Amended) An integrated burn-in test method for testing a multi-chip package, comprising:

providing the multi-chip package formed of multiple types kinds of semiconductor devices; and

in test program is adapted to test each of the semiconductor devices.

22. (Currently Amended) The method of claim 21, wherein the testing includes applying a specific test condition during testing of each of the semiconductor devices, wherein the specific test condition is defined by a multiplexer selection function.

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- 23. (Original) The method of claim 21, wherein the testing includes blocking some I/O terminals during testing of some semiconductor devices, wherein the blocking is defined by an I/O masking function.
- 24. (Currently Amended) The method of claim 21, wherein the testing includes setting a specific burn-in temperature condition for different types each of the semiconductor devices.
- 25. (Currently Amended) The method of claim 21, wherein the testing includes performing a <u>single</u> contact test once for all different types of semiconductor devices of the multi-chip package.
- 26. (Currently Amended) The method of claim 21, further comprising:
 <u>a one time</u> bin sorting once for all different types of semiconductor devices of for the multi-chip package based on the testing result.
- 27. (Currently Amended) An integrated burn-in test method for testing a multi-chip package, comprising:

providing the multi-chip package formed of multiple types kinds of semiconductor devices;

testing the multi-chip package with an integrated burn-in test program adapted to test each of the semiconductor devices, including

performing a <u>single</u> contact test once for all different types <u>each</u> of <u>the</u> semiconductor devices of the multi-chip package,

blocking some I/O terminals during testing of some semiconductor devices, wherein the blocking is defined by an I/O masking function,

setting a specific burn-in temperature condition for different types each of the semiconductor devices,

conducting a burn-in test for the multiple types of semiconductor devices the multi-chip package by applying a specific test condition for each of the semiconductor devices, wherein the specific test condition is defined by a multiplexer selection function; and

<u>a one time</u> bin sorting once for all different types of semiconductor devices of the multi-chip package based on the testing result.

- 28. (Currently Amended) The method of claim 1, further comprising:

 loading the multi-chip package formed of multiple kinds of semiconductor

 devices, to a chamber of the burn-in equipment capable of applying a plurality of scan
 control clock signals.
- 29. (Currently Amended) The method of claim 14, further comprising: loading the multi chip-package including different kinds of semiconductor devices on the burn-in board; and

loading the burn-in board into a chamber of the burn-in equipment capable of applying a plurality of scan control clock signals.